**APPLICATION FORM FOR INTERNATIONAL ADMISSION**

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| **Full Name(both English and Chinese)****\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_**Family Given Middle Former(if any) | **PRC Citizen ID****/ Passport ID** | **photo** |
| **Gender:**1. Male
2. Female
 | **Birthdate****\_\_\_\_\_-\_\_\_\_\_-\_\_\_\_\_**Month Day Year | **Birthplace****\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_**City State Country |
| **Mailing Address (Chinese)** Valid until\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_Daytime Phone: | **Email Address****Mobile Phone** |
| **Citizenship:**1. China
2. Other
 |
| **Education** List all colleges and universities attended |
| University:Department:Major:Date Attended:Degree/Date Received:GPA:Comprehensive Ranking(Rank/total number compared):综合排名: / Academic Ranking(Rank/total number compared):专业排名: /  | University: Department:Major:Date Attended:Degree/Date Received :GPA:Comprehensive Ranking(Rank/total number compared):综合排名: / Academic Ranking(Rank/total number compared):专业排名: /  |
| **Employer**\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_Company Name Location Position / Title From / To\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_Company Name Location Position / Title From / To |
| **Proposed Program( Master/PhD), Major and Direction 请填写你意向攻读的专业和方向** |
| □**PhD** □**Master** |
| **Majors** | **Research Discipline Group** |
| □**Mechanics**□**Mechanical Engineering**□**Power Engineering and Engineering Thermophysics**□**Electronic Science and Technology**□**Information and Communication Engineering**□**Control Science and Engineering**□**Computer Science and Technology** | □**Design, Manufacturing, and Systems**□**Solid Mechanics**□**Thermal Fluids**□**Material Science & Engineering**□**Circuits and Devices**□**Electromagnetics, Optics, and Photonics**□**Communications, Signal Processing**□**Computer Science and Engineering**□**Control** |
| **If you have taken any English test, please provide the name of test and your score** |
| **English Proficiency** |
| **TOEFL**Month/Year\_\_\_\_\_\_\_\_\_\_\_Score\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ | **IELTS**Month/Year\_\_\_\_\_\_\_\_\_\_\_Score\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ | **GRE** Month**/** Year \_\_\_\_ \_\_\_**\_\_\_\_\_\_\_\_\_ \_\_\_\_\_\_\_\_\_ \_\_\_\_\_\_\_\_\_**Verbal Quantitative Analytical |
| **Scholarships / Fellowships / Awards / Honors / Publications (Proof materials should be enclosed.)**Scholarships and fellowshipsMajor academic recognitions, honors, and memberships Significant professional activities and accomplishmentsSignificant extracurricular activities Titles of publications, major papers, or theses authored or co-authored; if published, provide citation (Reprints included with the application cannot be returned.) |
| **Recommendations** Provide information of persons to whom you have submitted requests for recommendations.Name Title Institution Department Email TelephoneName Title Institution Department Email Telephone |
| **Certification and Signature**I certify that I have answered all of the questions completely and truthfully. I understand that misrepresentation of any portion of this application, including supporting credentials and documents, may be cause for cancelling my admission, financial award, or appointment. I also understand that all credentials and documents that I submit become the property of Shanghai Jiao Tong University.**\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_****Signature Date** |